

CLAIMS

1. Information storage medium, this medium comprising an approximately plane front face (32) and a back face (30), this medium being designed to be read and/or written by a read and/or write device (46)
5 placed facing the front face, this medium being characterised in that the back face comprises recessed areas (28, 68, 69) and in that all or part of the sidewalls and/or the bottom of these recessed areas is covered with a magnetic deposit (34, 60, 62, 74, 82)
10 that will be used for information storage, the distance separating the front face from the magnetic deposit being such that the read and/or write device can read and/or write the information in the magnetic deposit.

15 2. Medium according to claim 1, in which the back face of the medium is fixed to a substrate (37, 78, 84).

3. Method for manufacturing an information storage
20 medium according to claim 1, in which the medium is formed comprising the approximately plane front face (32), the back face (30) and a discrete information storage array on this back face, in the form of recessed areas (28, 68, 69) provided with a magnetic
25 deposit (34, 60, 62, 74, 82), each recessed area being capable of containing at least one magnetic domain representing an elementary bit defined by a magnetisation direction.

4. Method according to claim 3, in which the back face also comprises areas (54, 56, 58) capable of making the medium stiff.

5 5. Method according to either of claims 3 and 4, in which the magnetic deposit (34, 60) is formed in the bottom of the recessed areas using a beam (F1) of atoms of at least one magnetic material directed onto the back face of the medium, perpendicular to this back
10 face.

6. Method according to any one of claims 3 to 5, in which the magnetic deposit (64) is formed on all or part of the sidewalls of the recessed areas using a
15 beam (F2) of atoms of at least one magnetic material directed onto the back face of the medium, oblique to this face.

7. Method according to any one of claims 3 to 6,
20 in which the medium includes a substrate (26) and the recessed areas (28) are formed directly in this substrate.

8. Method according to any one of claims 3 to 6,
25 in which the medium comprises a first layer (67), a second layer (66) is formed on this first layer and recessed areas (68) are formed through this second layer such that the bottom of these recessed areas is formed by the first layer.

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9. Method according to any one of claims 3 to 8,
in which the recessed areas (69) are formed by etching
through an etching mask (70) previously formed on the
back face, the magnetic deposit (74) is then formed and
5 the etching mask is eliminated including the magnetic
deposit located on it due to the formation of the
magnetic deposit.

10. Method according to any one of claims 3 to 9,
10 in which the back face of the medium is fixed to an
auxiliary substrate (78), this medium being provided
with recessed areas comprising the magnetic deposit.

11. Method according to any one of claims 3 to 6,
15 in which a first layer (67a) is formed on a substrate
(80), a second layer (67) is formed on this first layer
and a third layer (66) is formed on the second layer
(67), the recessed areas (68) are formed through the
third layer such that the bottom of the recessed areas
20 is formed by the second layer, the magnetic deposit
(82) is formed in the recessed areas, the second layer
(67) is separated from the substrate (80), and the
recessed areas are closed off by a fourth layer (84).